

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|-----------------------------------|---|---------------------|
| In re Application of: |) | PATENT APPLICATION |
| |) | |
| Inventors: Wei Pan, Jer-Shen Maa, |) | |
| David R. Evans and Sheng |) | |
| Teng Hsu |) | |
| |) | |
| Serial No.: Not Yet Assigned |) | Attorney Docket No. |
| |) | SLA 0493 |
| Filed: Herewith |) | |
| |) | |
| Title: METHOD OF BARRIER METAL |) | |
| SURFACE TREATMENT PRIOR |) | |
| TO Cu DEPOSITION TO |) | |
| IMPROVE ADHESION AND |) | |
| TRENCH FILLING |) | |
| CHARACTERISTICS |) | |
| |) | |

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name; I believe that I am the original, first and sole inventor (if one name is listed below), or the first and joint inventor (if plural names are listed below), of the subject matter which is claimed and for which a patent is sought on the invention entitled,

**METHOD OF BARRIER METAL SURFACE TREATMENT PRIOR TO
Cu DEPOSITION TO IMPROVE ADHESION AND TRENCH
FILLING CHARACTERISTICS**

the specification of which (check applicable ones):

- ☒ is attached hereto;
- ☐ was filed with the above-identified "Filed" date and assigned the above-identified "Serial No.";
- ☐ was amended on (or amended through) _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by an amendment(s) referred to above. I acknowledge the duty to disclose information which is material to the examination of the application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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Date: 3/28/01

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Date:

03/28/01
